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PATENTS  
112055-0040

#17  
C.A.  
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re The Application of:  
David Chong et al.

Serial No.: 09/823,600

Filed: March 30, 2001

For: PACKAGING SYSTEM FOR DIE-  
UP CONNECTION OF A DIE-  
DOWN ORIENTED INTEGRATED  
CIRCUIT

)  
)  
) Examiner: Not yet assigned  
)

)  
) Art Unit: Not yet assigned  
)

Cesari and McKenna, LLP  
88 Black Falcon Avenue  
Boston, MA 02210  
May 1, 2002

**CERTIFICATE OF MAILING**

I hereby certify that the following paper is being deposited with the United States Postal Service as first-class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231, on May 1, 2002.

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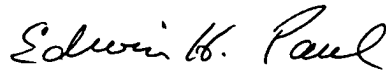
Pursuant to 37 C.F.R. §1.33(a), we request that the correspondence address for the above-identified patent application be changed to:

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Please charge any additional fee occasioned by this paper to our Deposit Account

No. 03-1237.

Respectfully submitted,



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